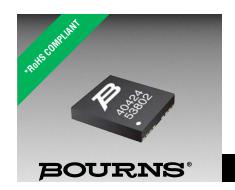
阅读申明

- 1.本站收集的数据手册和产品资料都来自互联网,版权归原作者所有。如读者和版权方有任何异议请及时告之,我们将妥善解决。
- 2.本站提供的中文数据手册是英文数据手册的中文翻译,其目的是协助用户阅读,该译文无法自动跟随原稿更新,同时也可能存在翻译上的不当。建议读者以英文原稿为参考以便获得更精准的信息。
- 3.本站提供的产品资料,来自厂商的技术支持或者使用者的心得体会等,其内容可能存在描 叙上的差异,建议读者做出适当判断。
- 4.如需与我们联系,请发邮件到marketing@iczoom.com,主题请标有"数据手册"字样。

Read Statement

- 1. The datasheets and other product information on the site are all from network reference or other public materials, and the copyright belongs to the original author and original published source. If readers and copyright owners have any objections, please contact us and we will deal with it in a timely manner.
- 2. The Chinese datasheets provided on the website is a Chinese translation of the English datasheets. Its purpose is for reader's learning exchange only and do not involve commercial purposes. The translation cannot be automatically updated with the original manuscript, and there may also be improper translations. Readers are advised to use the English manuscript as a reference for more accurate information.
- 3. All product information provided on the website refer to solutions from manufacturers' technical support or users the contents may have differences in description, and readers are advised to take the original article as the standard.
- 4. If you have any questions, please contact us at marketing@iczoom.com and mark the subject with "Datasheets".



Features

- Formerly **FullTec** brand
- Extremely high speed performance
- Low impedance
- Two TBU® protectors in one small package
- Very high bandwidth, GHz compatible
- Simple, superior circuit protection
- RoHS compliant*, UL Recognized 🔊

Applications

- xDSL (ADSL, VDSL, VDSL2)
- High Data Rate Interface IC protection (LVDS, HDMI, etc.)
- Industrial sensors and controls
- General electronics

P40-G Series TBU® High-Speed Protectors

Transient Blocking Units - TBU® Devices

Bourns® Model P40-G products are high-speed bidirectional protection components, constructed using MOSFET semiconductor technology, designed to protect against faults caused by short circuits, AC power cross, induction and lightning surges.

The TBU® high-speed protector, triggering as a function of the MOSFET, blocks surges and provides an effective barrier behind which sensitive electronics are not exposed to large voltages or currents during surge events. The TBU® device is provided in a surface mount DFN package and meets industry standard requirements such as RoHS and Pb Free solder reflow profiles.

Agency Approval

UL recognized component File # E315805.

Industry Standards

	Description					
Telcordia GR-1089		P40-G				
ITU-T	K.20, K.20E, K.21, K.21E, K.45	F40-G				

Absolute Maximum Ratings (Tamb = 25 °C)

Symbol	Parameter	Value	Unit
V _{imp}	Maximum protection voltage for impulse faults with rise time \geq 1 μ sec	40	V
V _{rms}	Maximum protection voltage for continuous V _{rms} faults	28	V
T _{op}	Operating temperature range	-55 to +125	°C
T _{stg}	Storage temperature range	-65 to +150	°C
T _{imax}	Maximum Junction Temperature	+125	°C

Electrical Characteristics (T_{amb} = 25 °C)

Symbol	Parameter	Min.	Тур.	Max.	Unit
I _{op}	Maximum current through the device that will not cause current blocking			240	mA
I _{trigger}	Typical current for the device to go from normal operating state to protected state		350		mA
l _{out}	Maximum current through the device			480	mA
R _{device}	Series resistance of the TBU® device		3.6	4.2	Ω
R _{bal}	Line-to line series resistance difference between two TBU® devices			5	%
t _{block}	Maximum time for the device to go from normal operating state to protected state			0.2	μs
I _{quiescent}	Current through the triggered TBU® device with 40 Vdc circuit voltage		0.7		mA
V _{reset}	Voltage below which the triggered TBU® device will transition to normal operating state		7		V
$R_{\theta JA}$	Junction to air thermal resistance, FR4 PCB. 0.035 sq. in. of copper in addition to solder pads		130		°C/W

The P40-G Series TBU® high-speed protector is bidirectional; specifications are valid in both directions.

Specifications are subject to change without notice.

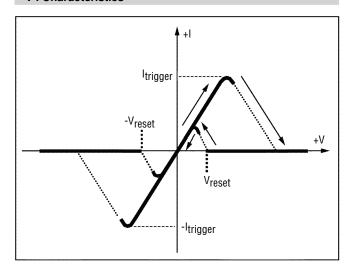
^{*}RoHS Directive 2002/95/EC Jan. 27, 2003 including annex and RoHS Recast 2011/65/EU June 8, 2011.

The device characteristics and parameters in this data sheet can and do vary in different applications and actual device performance may vary over time. Users should verify actual device performance in their specific applications.

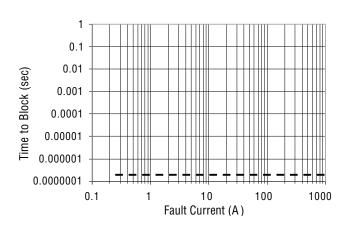
BOURNS

Typical Performance Characteristics

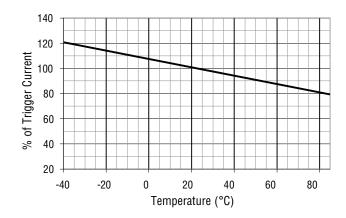
V-I Characteristics



Time to Block vs. Fault Current



Trigger Current vs. Temperature

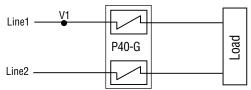


BOURNS

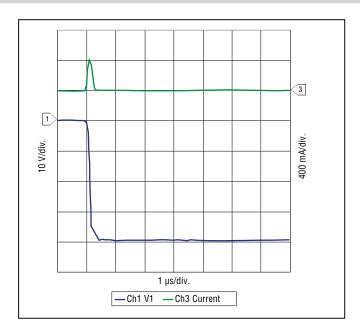
Operational Characteristics

The graph below demonstrates the operational characteristics of the TBU® device. In the graph below the fault voltage, protected side voltage, and current is presented.

TEST CONFIGURATION DIAGRAM

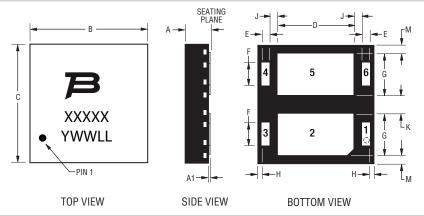


P40-G Lightning Protection 40 V

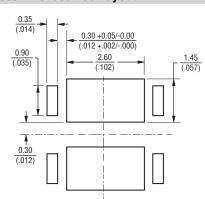


BOURNS

Product Dimensions



Recommended Pad Layout



Pad Designation

Apply
ln1
NC
Out1
Out2
NC
ln2

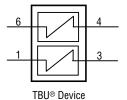
NC = Solder to PCB; do not make electrical connection, do not connect to ground.

TBU® devices have matte-tin termination finish. Suggested layout should use non-solder mask define (NSMD). Recommended stencil thickness is 0.10-0.12 mm (.004-.005 in.) with stencil opening size 0.025 mm (.0010 in.) less than the device pad size. As when heat sinking any power device, it is recommended that, wherever possible, extra PCB copper area is allowed. For minimum parasitic capacitance, do not allow any signal, ground or power signals beneath any of the pads of the device.

Dim.	Min.	Тур.	Max.
Α	<u>0.80</u>	<u>0.90</u>	1.00
	(.031)	(.035)	(.039)
A1	0.00	0.025	0.05
	(.000)	(.001)	(.002)
В	3.90	4.00	4.10
	(.154)	(.157)	(.161)
С	3.90	4.00	4.10
	(.154)	(.157)	(.161)
D	<u>2.55</u>	<u>2.60</u>	<u>2.65</u>
	(.100)	(.102)	(.104)
E	0.20	<u>0.25</u>	0.30
	(.008)	(.010)	(.012)
F	<u>0.75</u>	0.80	0.85
	(.030)	(.031)	(.033)
G	1.40	1.45	1.50
	(.055)	(.057)	(.059)
Н	0.10	0.15	0.20
	(.004)	(.006)	(.008)
J	0.25	0.30	0.35
	(.010)	(.012)	(.014)
K	0.55	0.60	0.65
	(.022)	(.024)	(.026)
М	$\frac{0.20}{(.008)}$	0.25 (.010)	0.30 (.012)

DIMENSIONS: $\frac{MM}{(INCHES)}$

Block Diagram



I DO DEVICE

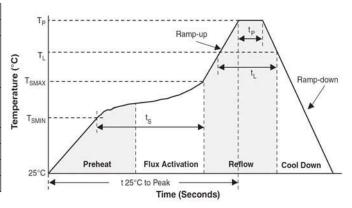
Thermal Resistances

Thermal resistance using minimal pad size, where the power is the total power dissipated in the package. Additional copper pad area to be used for additional heatsinking is also recommended.

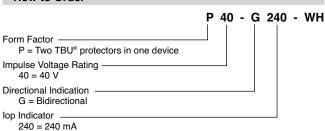
Symbol	Parameter	Value	Unit
Rth(j-a)	Junction to Package Pads (1 TBU of Pair)	250	°C/W
R _{th(j-a)}	Junction to Package Pads (2 TBUs of Equal Power)	180	°C/W

Reflow Profile

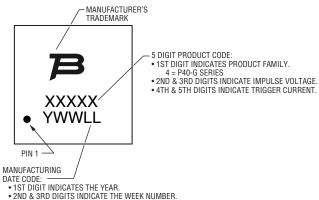
Profile Feature	Pb-Free Assembly			
Average Ramp-Up Rate (Tsmax to Tp)	3 °C/sec. max.			
Preheat - Temperature Min. (Tsmin) - Temperature Max. (Tsmax) - Time (tsmin to tsmax)	150 °C 200 °C 60-180 sec.			
Time maintained above: - Temperature (TL) - Time (tL)	217 °C 60-150 sec.			
Peak/Classification Temperature (Tp)	260 °C			
Time within 5 °C of Actual Peak Temp. (tp)	20-40 sec.			
Ramp-Down Rate	6 °C/sec. max.			
Time 25 °C to Peak Temperature	8 min. max.			



How to Order

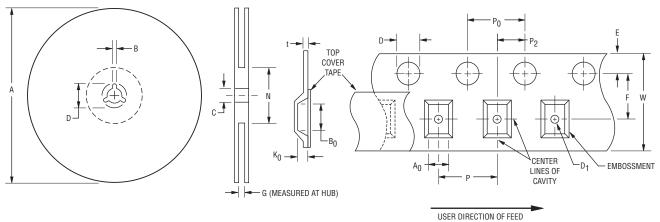


Typical Part Marking



- 4TH & 5TH DIGITS INDICATE LOT CODE.

Packaging Specifications (per EIA468-B)



QUANTITY: 3000 PIECES PER REEL

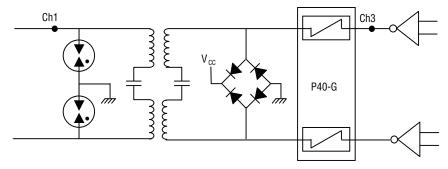
Device		A B		С		D		G	N	
Device	Min.	Max.	Min.	Max.	Min.	Max.	Min.	Max.	Ref.	Ref.
P40-G240	326 (12.835)	330.25 (13.002)	1.5 (.059)	2.5 (.098)	12.8 (.504)	13.5 (.531)	20.2 (.795)	ı	12.4 (.488)	102 (4.016)

Device	Min. Max. Min. Max.		E	B ₀ D)	D ₁		E		F	
Device			Min.	Max.	Min.	Max.	Min.	Max.	Min.	max.		
P40-G240	4.2 (.165)	4.4 (.173)	4.2 (.165)	4.4 (.173)	1.5 (.059)	1.6 (.063)	1.5 (.059)	-	1.65 (.065)	1.85 (.073)	<u>5.45</u> (.216)	<u>5.55</u> (.219)
	К	K ₀ P		P	P ₀		P ₂		t		W	
Device	Min.	Max.	Min.	Max.	Min.	Max.	Min.	Max.	Min.	Max.	Min.	Max.
P40-G240	1.05 (.041)	1.25 (.049)	7.9 (.311)	8.1 (.319)	3.9 (.159)	4.1 (.161)	1.9 (.075)	<u>2.1</u> (.083)	0.25 (.010)	0.35 (.014)	11.7 (.461)	12.3 (.484)

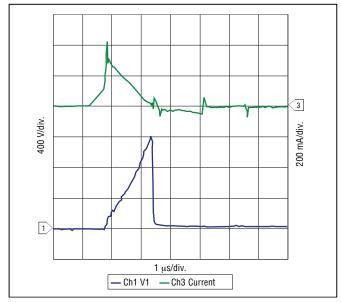
MM DIMENSIONS: (INCHES)

Reference Application

A cost-effective protection solution combines the Bourns® TBU® protection device with a diode bridge on the driver side of the transformer and GDTs on the line side. The GDT should have a minimum DCBD of 900 V and a maximum sparkover voltage of 1600 V. The diagram below illustrates a common configuration of these components. The graph demonstrates the operational characteristics of the circuit.



Common Configuration Diagram - xDSL Protection



5000 V Lightning 2/10 μsec, 500 A

BOURNS®

Asia-Pacific: Tel: +886-2 2562-4117 • Fax: +886-2 2562-4116

EMEA: Tel: +36 88 520 390 • Fax: +36 88 520 211

The Americas: Tel: +1-951 781-5500 • Fax: +1-951 781-5700

www.bourns.com

REV. 09/15

[&]quot;TBU" is a registered trademark of Bourns, Inc. in the United States and other countries.